

**In the Specification**

Please change the title to "Semiconductor Package Having Polymer Members Configured To Provide Selected Package Characteristics".

On page 2, line 1, add the following:

**--Cross Reference To Related Applications**

This application is a continuation of Serial No. 10/210,926, filed 08/02/2002, which is a continuation of Serial No. 09/841,221, filed 04/25/2001, Patent No. 6,440,772 B1, which is a division of Serial No. 09/454,503, filed 12/06/1999, Patent No. 6,384,487 B1. --

In the paragraph on page 13, lines 11-20, please make the following change.

--Prior to molding the outer member 44, the inner member 42 can be at least partially cured to provide an increased structural rigidity. For example, partial curing can be performed at a temperature of about 120°C-180°C for several minutes or more. In addition, the molding compound used to form the inner member 42 can include fillers selected to provide the outer member 44 with desired mechanical and electrical characteristics such as a relatively fast cure time, and an increased rigidity for strengthening the package body 18.--